

Fair-Rite P/N **2773008112**

73 Material Grade

Nominal Chemical Composition

<u>Compound</u>	<u>CAS Number</u>	<u>wt %</u>	Wt of core (g)= 0.523	Compound Weight (g) Breakdown of 73 Material
Fe2O3	1309-37-1	67	0.3504	
ZnO	1314-13-2	14	0.0732	
MnO	1344-43-0	19	0.0994	

Pb- Free Plated Round Cu Wire

<u>Element</u>	<u>CAS Number</u>	<u>wt%</u>	Wt of wire (g)= 0.177	Element Weight (g) Breakdown of Pb- Free Plated Round Cu Wire
Cu	7440-50-8	94.4	0.16709	
Plating:				
Ni	7440-02-0	0.9	0.00159	
Sn	7440-31-5	4.7	0.00832	

Calculated Maximum Levels of RoHS Restricted Substances Present in 73 Material Grade

<u>Impurity Substance</u>	<u>RoHS Threshold (ppm)</u>	<u>ppm</u>	Wt of core (g)= 0.523	RoHS Impurity Substance Weight (g) Breakdown of 73 Material
Cr+6	1000	0.00	0	
Cd	100	3.70	1.94E-06	
Hg	1000	0.10	5.23E-08	
Pb	1000	8.25	4.31E-06	
PBB	1000	0.00	0	
PBDE	1000	0.00	0	
Bis(2-Ethylhexyl) phthalate (DEHP)	1000	0.00	0	
Benzyl butyl phthalate (BBP)	1000	0.00	0	
Dibutyl phthalate (DBP)	1000	0.00	0	
Diisobutyl phthalate (DIBP)	1000	0.00	0	

Supporting notes:

- P/N 2773008112 consists of:
 - core 73 Material Grade
 - wire Pb- Free Plated Round Cu Wire
- Moisture Sensitivity Level (MSL)= 1
- Max Reflow Temp= 260 degC
- Max Time at Max Reflow Temp= 40 sec
- RoHS 6/6 Compliant Terminations/ Wire are backwards compatible with standard Soldering Processes
- RoHS Conversion Date= 1/1/2005
- RoHS Compliance Marking is Contained on Shipping Labels